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Application ID:

09667720

Title of Invention:

RF Active Compositions For Use In Adhesion, Bonding And

Coating

First Named Inventor:

William J. Ryan

Domestic/Foreign Application:

Domestic Application

Filing Date:

2000-09-22

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2004-02-04

Submission Type:

Information Disclosure

Statement

Filing Type:

Confirmation number:

9377

Attorney Docket Number:

2113.0040004

Total Fees Authorized:

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TRANSMITTAL

Exectronic Version v1.1

TRADEM Stylesheet Version v1.1.0

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William J. Ryan

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Submitted by:	Elec. Sign.	Sign. Capacity
Aaron L. Schwartz Registered Number: 48181	Aaron L. SCHWARTZ	Agent

Documents being submitted

Files

us-ids

21130040004c-usidst.xml

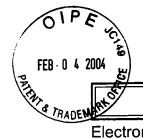
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Comments

This IDS is being filed as five separate submissions on the same day, four

electronically and one non-electronically. This is the third of the four electronic submissions. It is believed that only one fee under 37 C.F.R. section 1.17(p) is required to cover all submissions. That fee has been included with the first electronic submission.



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18 Stylesheet Version v18.0

> Title of Invention

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09/667720

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First Named Applicant:

William J. Ryan

Attorney Docket Number: 2113.0040004

Art Unit:

1714

Examiner:

Patrick Dennis Niland

Search string:

(5300749 or 5336346 or 5393351 or 5403123 or 5413837 or 5429702 or 5447592 or 5458233 or 5469863 or 5499484 or 5529708 or 5534097 or 5541482 or 5548056 or 5567489 or 5587226 or 5611882 or 5620656 or 5644798 or 5646076 or 5667621 or 5679423 or 5693412 or 5698061 or 5698062 or 5712044 or 5732413 or 5766400 or 5766744 or 5804021 or 5806983 or 5824606 or 5833915 or 5840405 or 5846620 or 5861211 or 5882789 or 5893219 or 5912317 or 5945486 or 5989375 or 6023856 or 6025287 or 6030490 or 6042673 or 6045648 or 6052033 or 6060145

or 6074704).pn.

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Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Signature

Examiner Name	Date
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